Very Low I_q Low Dropout Linear Regulator

The NCV8664C is a precision 3.3 V and 5.0 V fixed output, low dropout integrated voltage regulator with an output current capability of 150 mA. Careful management of light load current consumption, combined with a low leakage process, achieve a typical quiescent current of $22~\mu A$.

NCV8664C is pin and functionally compatible with NCV4264–2C and could replace this part when lower quiescent current is required.

The output voltage is accurate within ± 2.0 %, and maximum dropout voltage is 600 mV at full rated load current.

It is internally protected against input supply reversal, output overcurrent faults, and excess die temperature. No external components are required to enable these features.

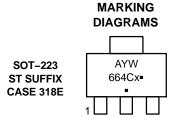
Features

- 3.3 V, 5.0 V Fixed Output
- ±2.0 % Output Accuracy, Over Full Temperature Range
- 22 μA Typical Quiescent Current
- 600 mV Maximum Dropout Voltage at 150 mA Load Current
- Wide Input Voltage Operating Range of 4.5 V to 45 V
- Internal Fault Protection
 - → -42 V Reverse Voltage
 - ◆ Short Circuit/Overcurrent
 - Thermal Overload
- EMC Compliant
- AEC-Q100 Grade 1 Qualified and PPAP Capable
- These are Pb-Free Devices



ON Semiconductor®

www.onsemi.com



x = Voltage Rating SOT223

(5 = 5.0 V Version)(3 = 3.3 V Version)

A = Assembly Location

Y = Year
W = Work Week
Pb-Free Package

TAB

(Note: Microdot may be in either location)

PIN CONNECTIONS

(SOT-223)
PIN FUNCTION
1 V_{IN}
2,4,TAB GND
3 V_{OUT}

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 10 of this data sheet.

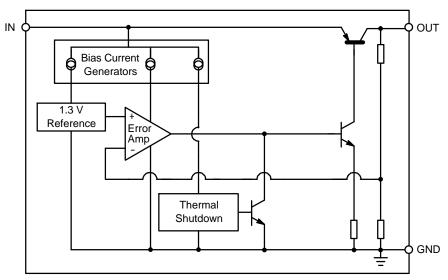


Figure 1. Block Diagram

PIN FUNCTION DESCRIPTION

Pin No.		
SOT-223	Symbol	Function
1	V _{IN}	Unregulated input voltage; 4.5 V to 45 V.
2	GND	Ground; Must be connected to GND potential.
3	V _{OUT}	Regulated output voltage.
4, TAB	GND	Ground; substrate and best thermal connection to the die.

OPERATING RANGE

Pin Symbol, Parameter	Symbol	Min	Max	Unit
V _{IN} , DC Input Operating Voltage	V _{IN}	4.5	+45	V
Junction Temperature Operating Range	TJ	-40	+150	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

MAXIMUM RATINGS

Rating	Symbol	Min	Max	Unit
V _{IN} , DC Voltage	V _{IN}	-42	+45	V
V _{OUT} , DC Voltage	V _{OUT}	-0.3	+32	V
Storage Temperature	T _{stg}	- 55	+150	°C
ESD Capability, Human Body Model (Note 1)	V _{ESDHBM}	4	-	kV
ESD Capability, Machine Model (Note 1)	V _{ESDMIM}	200	-	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ESD HBM tested per AEC-Q100-002 (EIA/JESD22-A 114C) ESD MM tested per AEC-Q100-003 (EIA/JESD22-A 115C)

^{1.} This device series incorporates ESD protection and is tested by the following methods:

THERMAL RESISTANCE

Parameter		Symbol Condition		Min	Max	Unit
Junction-to-Ambient	SOT-223	$R_{ heta JA}$		-	109 (Note 2)	°C/W
Junction-to-Tab	SOT-223	R_{\psiJT}		-	10.9	°C/W

^{2. 1} oz copper, 100 mm² copper area, FR4.

LEAD SOLDERING TEMPERATURE AND MSL

Rating	Symbol	Min	Max	Unit	
Lead Temperature Soldering Reflow (SMD Styles Only), Lead Free (Note 3)		T _{sld}	-	265 pk	ô
Moisture Sensitivity Level	SOT223	MSL	3	-	-

^{3.} Lead Free, 60 sec – 150 sec above 217°C, 40 sec max at peak.

ELECTRICAL CHARACTERISTICS ($V_{IN} = 13.5 \text{ V}$, $T_{j} = -40^{\circ}\text{C}$ to +150°C, unless otherwise noted.)

Characteristic	Characteristic Symbol Test Conditions		Min	Тур	Max	Unit
Output Voltage 5.0 V Version	V _{OUT}	$0.1 \text{ mA} \le I_{OUT} \le 150 \text{ mA (Note 4)}$ $6.0 \text{ V} \le V_{IN} \le 28 \text{ V}$	4.900	5.000	5.100	V
Output Voltage 5.0 V Version	Vouт	$\begin{array}{l} 0 \text{ mA} \leq I_{OUT} \leq 150 \text{ mA} \\ 5.5 \text{ V} \leq \text{V}_{IN} \leq 28 \text{ V} \\ -40^{\circ}\text{C} \leq \text{T}_{J} \leq 125^{\circ}\text{C} \end{array}$	4.900	5.000	5.100	V
Output Voltage 3.3 V Version	V _{OUT}	0.1 mA \leq I _{OUT} \leq 150 mA (Note 4) 4.5 V \leq V _{IN} \leq 28 V	3.234	3.300	3.366	V
Line Regulation 5.0 V Version	ΔV _{OUT} vs. V _{IN}	$I_{OUT} = 5.0 \text{ mA}$ 6.0 V $\leq V_{IN} \leq 28 \text{ V}$	-25	2.0	+25	mV
Line Regulation 3.3 V Version	ΔV _{OUT} vs. V _{IN}	$I_{OUT} = 5.0 \text{ mA}$ $4.5 \text{ V} \le V_{IN} \le 28 \text{ V}$	-25	2.0	+25	mV
Load Regulation	ΔV _{OUT} vs. I _{OUT}	1.0 mA ≤ I _{OUT} ≤ 150 mA (Note 4)	-35	5.0	+35	mV
Dropout Voltage 5.0 V Version	V _{IN} -V _{OUT}	I _Q = 100 mA (Notes 4 & 5) I _Q = 150 mA (Notes 4 & 5)	- -	240 270	500 600	mV
Quiescent Current	Iq	$I_{OUT} = 100 \mu A$ $T_{J} = 25^{\circ}C$ $T_{J} = -40^{\circ}C \text{ to } +85^{\circ}C$	_ _	21 22	29 30	μΑ
Active Ground Current	I _{G(ON)}	I _{OUT} = 50 mA (Note 4) I _{OUT} = 150 mA (Note 4)	- -	0.6 4.0	3 15	mA
Power Supply Rejection	PSRR	$V_{RIPPLE} = 0.5 V_{P-P}, F = 100 Hz$	_	67	-	dB

PROTECTION

Current Limit	I _{OUT(LIM)}	V _{OUT} = 4.5 V (5.0 V Version) (Note 4) V _{OUT} = 3.0 V (3.3 V Version) (Note 4)	150 150	- -	500 500	mA
Short Circuit Current Limit I _{OUT(SC)}		V _{OUT} = 0 V (Note 4)	100	-	500	mA
Thermal Shutdown Threshold	T _{TSD}	(Note 6)	150	ı	200	°C

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{4.} Use pulse loading to limit power dissipation.

^{5.} Dropout voltage = $(V_{IN} - V_{OUT})$, measured when the output voltage has dropped 100 mV relative to the nominal value obtained with $V_{IN} = 13.5 \text{ V}$.

^{6.} Not tested in production. Limits are guaranteed by design.

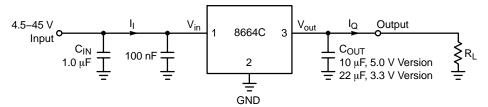


Figure 2. Measurement Circuit

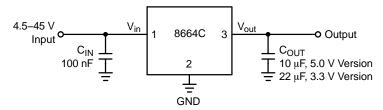
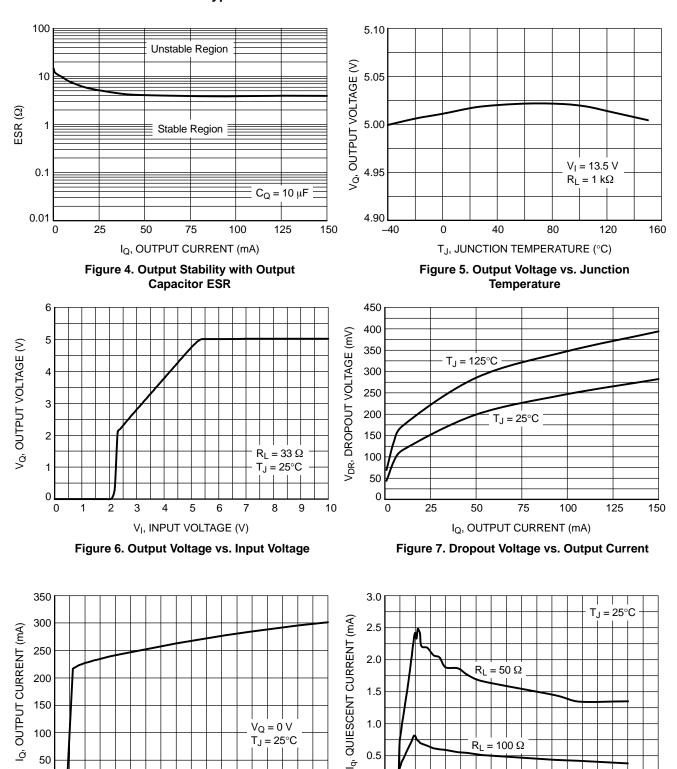


Figure 3. Applications Circuit

Typical Characteristic Curves - 5 V Version



V_I, INPUT VOLTAGE (V) Figure 8. Maximum Output Current vs. Input Voltage

V_I, INPUT VOLTAGE (V) Figure 9. Quiescent Current vs. Input Voltage

 $R_I = 100 \Omega$

1.0

0.5

 $V_Q = 0 V$

 $T_J = 25^{\circ}C$

Typical Characteristic Curves – 5 V Version

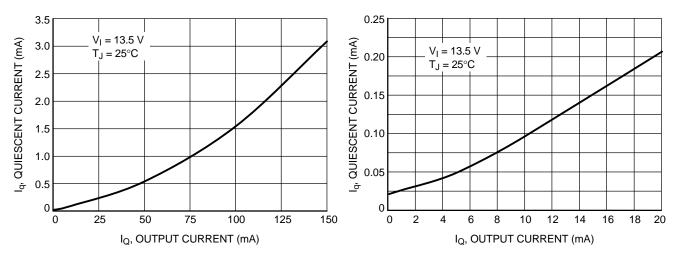


Figure 10. Quiescent Current vs. Output Current, (High Load)

Figure 11. Quiescent Current vs. Output Current, (Low Load)

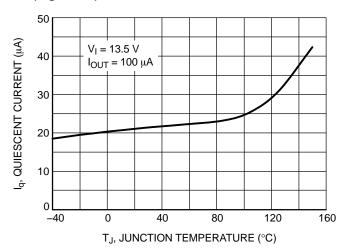
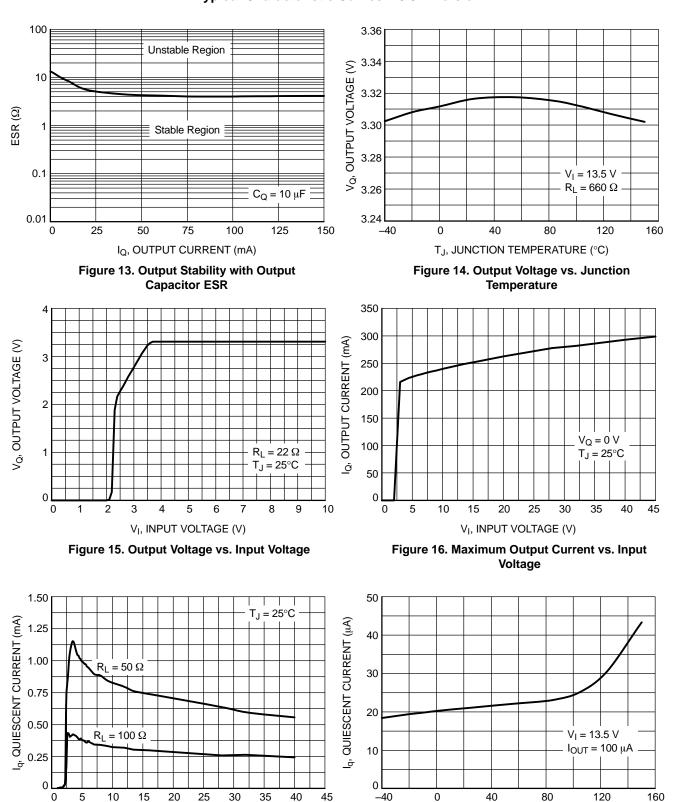


Figure 12. Quiescent Current vs. Temperature

Typical Characteristic Curves - 3.3 V Version



 $\label{eq:VI} V_{I}, \text{INPUT VOLTAGE (V)}$ Figure 17. Quiescent Current vs. Input Voltage

T_J, JUNCTION TEMPERATURE (°C) Figure 18. Quiescent Current vs. Temperature

Typical Characteristic Curves – 3.3 V Version

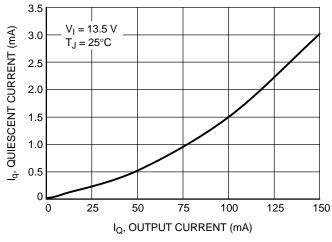


Figure 19. Quiescent Current vs. Output Current, (High Load)

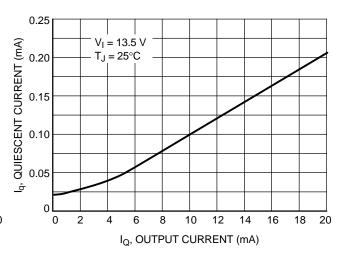


Figure 20. Quiescent Current vs. Output Current, (Low Load)

Circuit Description

The NCV8664C is a precision trimmed 3.3 V and 5.0 V fixed output regulator. Careful management of light load consumption combined with a low leakage process results in a typical quiescent current of 22 μA. The device has current capability of 150 mA, with 600 mV of dropout voltage at full rated load current. The regulation is provided by a PNP pass transistor controlled by an error amplifier with a bandgap reference. The regulator is protected by both current limit and short circuit protection. Thermal shutdown occurs above 150°C to protect the IC during overloads and extreme ambient temperatures.

Regulator

The error amplifier compares the reference voltage to a sample of the output voltage (V_{out}) and drives the base of a PNP series pass transistor by a buffer. The reference is a bandgap design to give it a temperature–stable output. Saturation control of the PNP is a function of the load current and input voltage. Over saturation of the output power device is prevented, and quiescent current in the ground pin is minimized. The NCV8664C is equipped with foldback current protection. This protection is designed to reduce the current limit during an overcurrent situation.

Regulator Stability Considerations

The input capacitor C_{IN} in Figure 2 is necessary for compensating input line reactance. Possible oscillations caused by input inductance and input capacitance can be damped by using a resistor of approximately 1 Ω in series with C_{IN}. The output or compensation capacitor, C_{OUT} helps determine three main characteristics of a linear regulator: startup delay, load transient response and loop stability. The capacitor value and type should be based on cost, availability, size and temperature constraints. Tantalum, aluminum electrolytic, film, or ceramic capacitors are all acceptable solutions, however, attention must be paid to ESR constraints. The aluminum electrolytic capacitor is the least expensive solution, but, if the circuit operates at low temperatures (-25° C to -40° C), both the value and ESR of the capacitor will vary considerably. The capacitor manufacturer's data sheet usually provides this information. The value for the output capacitor COUT shown in Figure 2 should work for most applications; however, it is not necessarily the optimized solution. Actual Stability Regions are shown in the graphs in the Typical Performance Characteristics section.

Calculating Power Dissipation in a Single Output Linear Regulator

The maximum power dissipation for a single output regulator (Figure 3) is:

$$PD(max) = [VIN(max) - VOUT(min)] \cdot IQ(max) + VI(max) \cdot Iq$$
 (eq. 1)

Where:

V_{IN(max)} is the maximum input voltage,

V_{OUT(min)} is the minimum output voltage,

 $I_{Q(max)}$ is the maximum output current for the application, and I_q is the quiescent current the regulator consumes at $I_{Q(max)}$.

Once the value of $P_{D(Max)}$ is known, the maximum permissible value of $R_{\theta JA}$ can be calculated:

$$P_{\theta JA} = \frac{150^{\circ}C - T_{A}}{P_{D}} \tag{eq. 2}$$

The value of $R_{\theta JA}$ can then be compared with those in the package section of the data sheet. Those packages with $R_{\theta JA}$'s less than the calculated value in Equation 2 will keep the die temperature below 150°C. In some cases, none of the packages will be sufficient to dissipate the heat generated by the IC, and an external heat sink will be required. The current flow and voltages are shown in the Measurement Circuit Diagram.

Heat Sinks

A heat sink effectively increases the surface area of the package to improve the flow of heat away from the IC and into the surrounding air. Each material in the heat flow path between the IC and the outside environment will have a thermal resistance. Like series electrical resistances, these resistances are summed to determine the value of $R_{\theta IA}$:

$$R_{\theta}JA = R_{\theta}JC + R_{\theta}CS + R_{\theta}SA$$
 (eq. 3)

Where:

 $R_{\theta JC}$ = the junction-to-case thermal resistance,

 $R_{\theta CS}$ = the case-to-heat sink thermal resistance, and

 $R_{\theta SA}$ = the heat sink-to-ambient thermal resistance.

 $R_{\theta JC}$ appears in the package section of the data sheet. Like $R_{\theta JA}$, it too is a function of package type. $R_{\theta CS}$ and $R_{\theta SA}$ are functions of the package type, heatsink and the interface between them. These values appear in data sheets of heatsink manufacturers.

Thermal, mounting, and heat sinking are discussed in the ON Semiconductor application note AN1040/D, available on the ON Semiconductor Website.

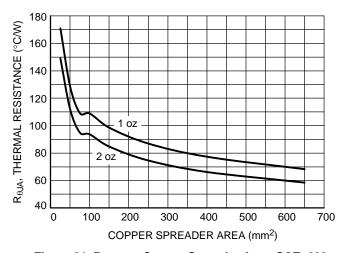


Figure 21. $R_{\theta JA}$ vs. Copper Spreader Area, SOT–223

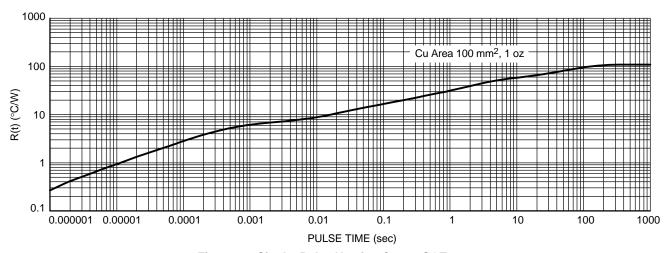


Figure 22. Single-Pulse Heating Curve, SOT-223

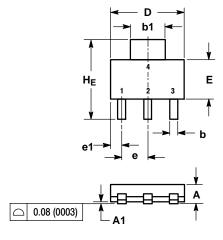
ORDERING INFORMATION

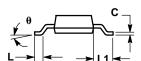
Device	Marking	Package	Shipping [†]
NCV8664CST50T3G	664C5	SOT-223 (Pb-Free)	4000 / Tape & Reel
NCV8664CST33T3G	664C3	SOT-223 (Pb-Free)	4000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04 ISSUE N



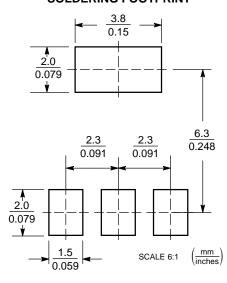


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: INCH.

	М	ILLIMETE	RS		INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
С	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
е	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L	0.20			0.008		
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	_	10°	0°	_	10°

SOLDERING FOOTPRINT



ON Semiconductor and the 👊 are registered trademarks of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries. SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent- Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA **Phone**: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your loca Sales Representative